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## AO7405

# P-Channel Enhancement Mode Field Effect Transistor

# **General Description**

The AO7405 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge, and operation with gate voltages as low as 2.5V, in the small SOT363 footprint. It can be used for a wide variety of applications, including load switching, low current inverters and low current DC-DC converters.

#### **Features**

 $V_{DS}(V) = -30V$ 

 $I_{D} = -1.6A$ 

 $R_{DS(ON)}$  < 150m $\Omega$  ( $V_{GS}$  = -10V)

 $R_{DS(ON)}$  < 200m $\Omega$  (V<sub>GS</sub> = -4.5V)

 $R_{DS(ON)}$  < 280m $\Omega$  (V<sub>GS</sub> = -2.5V)



Absolute Maximum Ratings T <sub>A</sub> =25°C unless otherwise noted								
Parameter		Symbol	Maximum	Units				
Drain-Source Voltage		$V_{DS}$	-30	V				
Gate-Source Voltage		$V_{GS}$	±12	V				
Continuous Drain	T <sub>A</sub> =25°C		-1.6					
Current <sup>A</sup>	T <sub>A</sub> =70°C	$I_D$	-1.3	А				
Pulsed Drain Current <sup>B</sup>		I <sub>DM</sub>	-10					
	T <sub>A</sub> =25°C	P <sub>D</sub>	0.625	W				
Power Dissipation A	T <sub>A</sub> =70°C	T D	0.4	VV				
Junction and Storage Temperature Range		$T_J$ , $T_{STG}$	-55 to 150	°C				

Thermal Characteristics								
Parameter	Symbol	Тур	Max	Units				
Maximum Junction-to-Ambient A	t ≤ 10s	В		200	°C/W			
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State	$ R_{\theta JA}$		220	°C/W			
Maximum Junction-to-Lead <sup>C</sup>	Steady-State	$R_{ heta JL}$			°C/W			

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
STATIC I	PARAMETERS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-30			V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1	μА	
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			-5 ±100	nA	
V <sub>GS(th)</sub>	Gate Threshold Voltage $V_{DS} = V_{GS} I_D = -250 \mu A$		-0.6	-1	-1.4	V	
	On state drain current	$V_{GS}$ =-4.5V, $V_{DS}$ =-5V	-10	<u> </u>		A	
R <sub>DS(ON)</sub> On state drain current  R <sub>DS(ON)</sub> Static Drain-Source On-Resistance	On state drain current	$V_{GS}$ =-10V, $I_{D}$ =-1.6A	10	115	150		
	Statio Drain Source On Resistance	T <sub>j</sub> =125°G		110	100	mΩ	
	Static Drain-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A		135	200	mΩ	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1A		190	280	mΩ	
<b>g</b> FS	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-1.2A	3	4.5		S	
$V_{SD}$	Diode Forward Voltage	I <sub>S</sub> =-1A,V <sub>GS</sub> =0V		-0.85	-1	V	
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-0.5	Α	
DYNAMI	CPARAMETERS						
C <sub>iss</sub>	Input Capacitance			409		pF	
C <sub>oss</sub>	Output Capacitance	$V_{GS}$ =0V, $V_{DS}$ =-15V, f=1MHz		55		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			42		pF	
$R_g$	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		12		Ω	
SWITCHI	NG PARAMETERS						
$Q_g$	Total Gate Charge			5.06		nC	
$Q_{gs}$	Gate Source Charge	$V_{GS}$ =-4.5V, $V_{DS}$ =-15V, $I_{D}$ =-1A		0.72		nC	
$Q_{gd}$	Gate Drain Charge			1.58		nC	
t <sub>D(on)</sub>	Turn-On DelayTime			6.2		ns	
t <sub>r</sub>	Turn-On Rise Time	$V_{GS}$ =-10V, $V_{DS}$ =-15V, $R_L$ =15 $\Omega$ ,		3.2		ns	
t <sub>D(off)</sub>	Turn-Off DelayTime	$R_{GEN}$ =3 $\Omega$		41.2		ns	
t <sub>f</sub>	Turn-Off Fall Time	]		14.5		ns	
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-1A, dI/dt=100A/μs		13.2		ns	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-1A, dI/dt=100A/μs		5.4		nC	

A: The value of  $R_{\theta JA}$  is measured with the device mounted on  $1\text{in}^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25°C. The value in any a given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R  $_{\theta JA}$  is the sum of the thermal impedence from junction to lead R  $_{\theta JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using  $80\,\mu s$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in  $^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25°C. The SOA curve provides a single pulse rating.